

**REMARKS**

Claims 1-13 are pending. The specification is amended hereby. Non-elected claims 14-16 are canceled without prejudice or disclaimer. A marked-up version showing the changes to the specification is attached hereto as "**Version with markings to show changes made.**"

Entry of the amendments to the specification after final rejection is requested to correct grammatical and clerical errors. More specifically, applicants have noted that Table 2 of the originally filed application was the same as Table 1. As such, the correct Table 2 is provided to report the peel strength. No new matter is added since the specification provides all of the conditions to obtain the peel strength reported in Table 2. A declaration of Masaru Nishinaka is submitted herewith repeating the experiments of Example 2 and Comparative Example 2 as provided in the specification.

Claims 1-9 were rejected under 35 U.S.C. §103(a) as being unpatentable over Chen et al. or Shiotani et al. This rejection is respectfully traversed.

During a telephone interview conducted with the Examiner and the undersigned attorney on November 27, 2002, the language of claim 1 was emphasized of "forming at least one conductor layer directly on at least one of the thermoplastic polyimide surfaces." It was pointed that both Chen et al. and Shiotani et al. do not directly form their metal layer on polyimide, but instead laminate a previously formed metal layer onto the polyimide. It is respectfully submitted that the present language does not include the laminating employed by the prior art. In other words, in Chen et al.

or Shiotani et al, the metal layer is first formed and then is later laminated, whereas in the present invention, the conductor layer is formed directly on the polyimide surface.

Claims 10-13 were rejected under 35 U.S.C. §103(a) as being unpatentable over Chen et al. or Shiotani et al. This rejection is respectfully traversed.

It appears that the Examiner intended to include Ameen et al. in the rejection. Ameen et al. discloses an electrode deposited copper foil on Kapton.

It is respectfully submitted that Ameen et al. fails to provide the teachings which Chen et al. and Shiotani et al. lack, as discussed above.

Ameen et al. discloses a laminate wherein a conductor layer is formed on a substrate by a sputtering method or an evaporation method. Ameen et al. does not entirely disclose a thermoplastic polyimide.

In contrast thereto, a conductor layer is formed directly on a thermoplastic polyimide surface in the present invention and the laminate is heated so that a polyimide and a conductor layer are directly thermally fused. Accordingly, the adhesion strength between the thermoplastic polyimide and the conductor layer is enhanced.

Applicants have compared the adhesion strength of the laminate in the present invention with that of the laminate which does not include the thermoplastic polyimide in accordance with Ameen et al. The results of the comparison are set forth in the attached Declaration under 37 CFR §1.132.

For at least the foregoing reasons, the claimed invention distinguishes over the cited art and defines patentable subject matter. Favorable reconsideration is earnestly solicited.

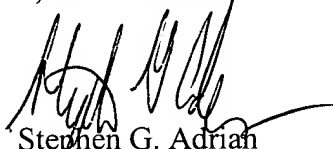
U.S. Patent Application Serial No. 09/782,169

Should the Examiner deem that any further action by applicants would be desirable to place the application in condition for allowance, the Examiner is encouraged to telephone applicants' undersigned attorney.

In the event that this paper is not timely filed, Applicants respectfully petition for an appropriate extension of time. Please charge any fees for such an extension of time and any other fees which may be due with respect to this paper, to Deposit Account No. 01-2340.

Respectfully submitted,

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PATENT TRADEMARK OFFICE

Enclosures: Version with markings to show changes made  
Declaration under 37 CFR 1.132  
Declaration  
Petition for Extension of Time

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**IN THE SPECIFICATION:**

Please amend the specification as follows:

**Paragraph beginning at page 5, line 16 has been amended as follows:**

- (8) The process according to any one of (1) to (3), wherein said heating step is carried out under [the pressurized condition] pressure.

**Paragraph beginning at page 5, line 21 has been amended as follows:**

- (10) The process according to any one of (1) to (3), wherein said conductor layer is formed by a dry plating method.

**Table 2 beginning on line 9 of page 20, has been replaced with the following Table**

**2:**

**[Table 2]**

	Heating temp. (°C)	Peel strength (N/cm)
Ex. 2	170	4.2
	220	4.4
Comp. Ex. 2	no	1.8